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Patent and Trademark Office

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Wen-Ying WEN

Additional name(s) of conveying parties attached? ☐ YES ☒ NO

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- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: August 13, 1999

2. Name and address of receiving parties:

Name: WINBOND ELECTRONICS CORP.

Internal Address: _____

Street Address: NO. 4 CREATION RD. III
SCIENCE-BASED INDUSTRIAL PARKCity: HSINCHU State: _____Zip: _____ Country: TAIWAN, R.O.C.Additional name(s) & address(es) attached? ☐ YES ☒ NO

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No(s):

09/607,769

B. Patent No(s):

Additional numbers attached? ☐ YES ☒ NO

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Richard P. Berg
LADAS & PARRY

Internal Address: _____

Street Address: 5670 Wilshire Boulevard, #2100City: Los Angeles State: CA Zip: 900366. Total number of application and patents involved: [1]7. Total fee 937 CFR 3.41).....\$ 40.00☒ Enclosed

Any additional fees which may be required are

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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Name of Person Signing
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PATENT
REEL: 011030 FRAME: 0156

ASSIGNMENT

WHEREAS, Wen-Ying WEN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD AND STRUCTURE FOR MANUFACTURING ROMs IN A SEMICONDUCTOR PROCESS

Filed: June 30, 2000

Serial No. 09/607,769

Executed on: August 13, 1999

WHEREAS, Winbond Electronics Corp. of No. 4, Creation Rd. III, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Wen - Ying WEN
Wen-Ying WEN

8/13/99
Date: